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FIG. 1.

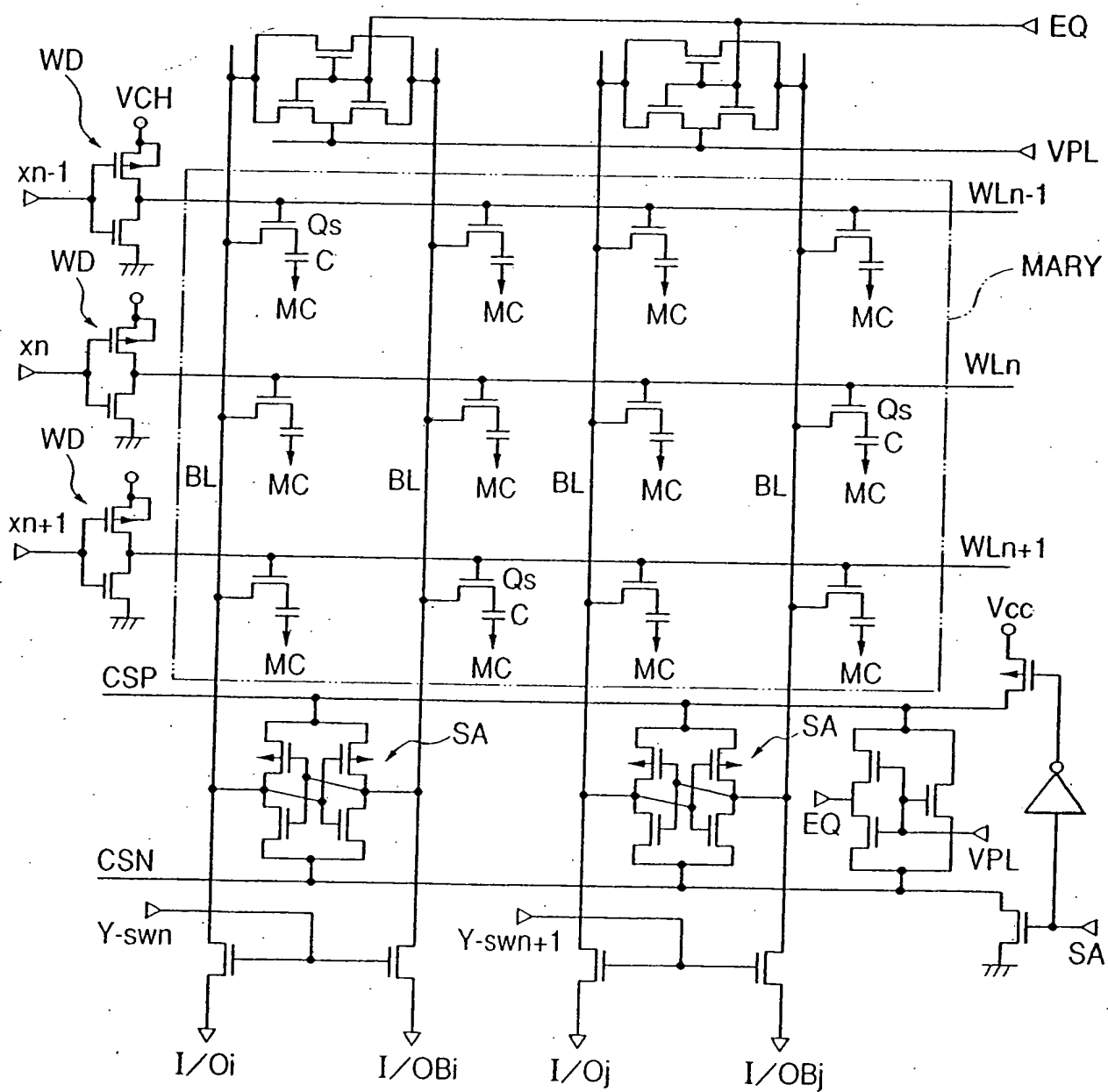


FIG. 2

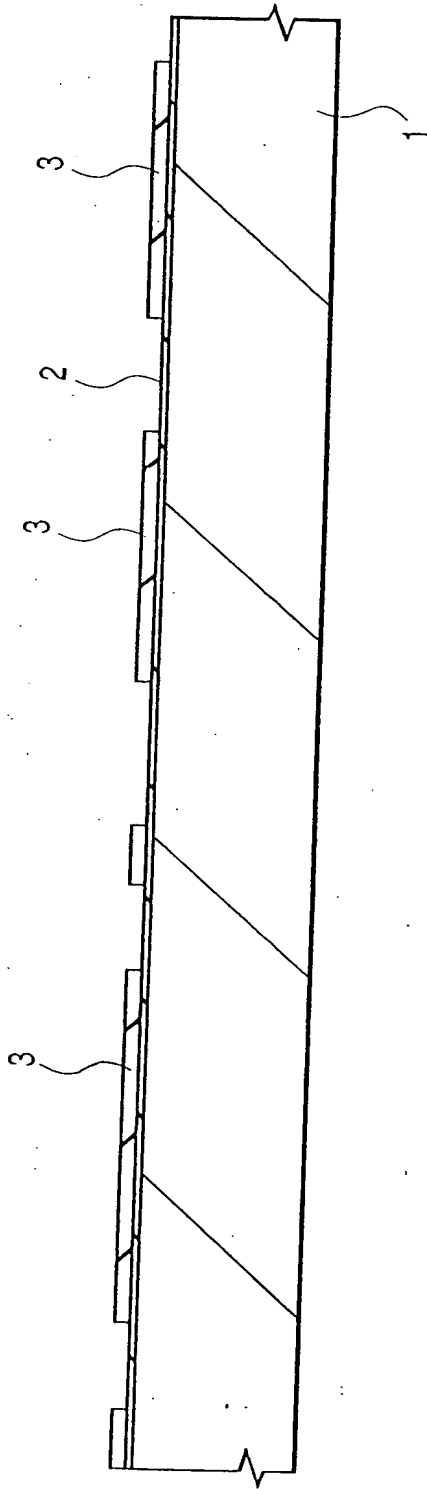


FIG. 3

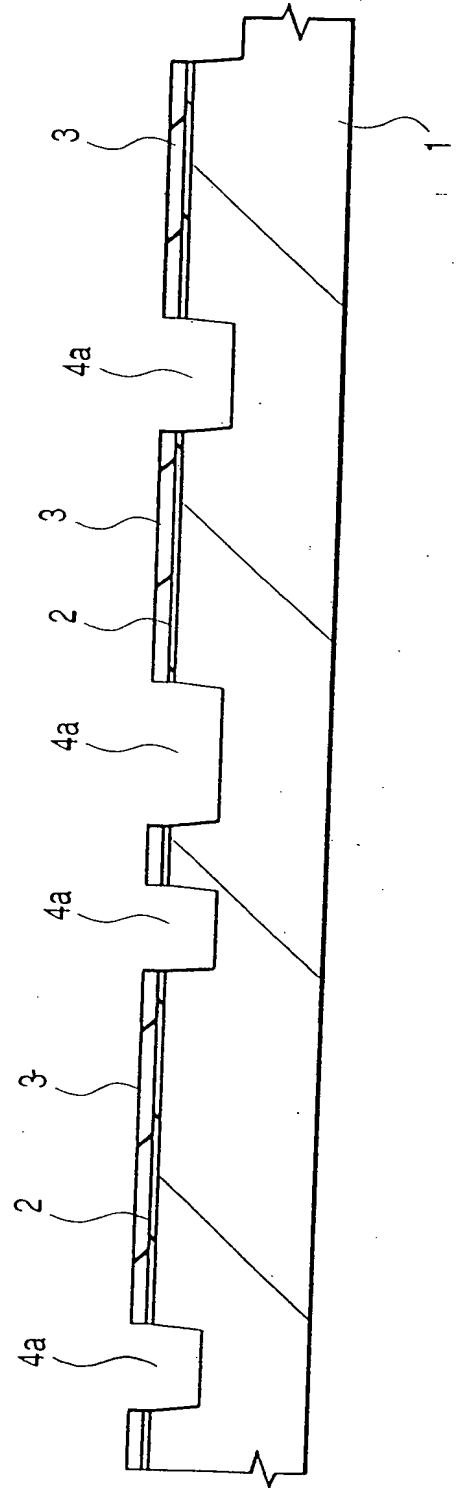


FIG. 4

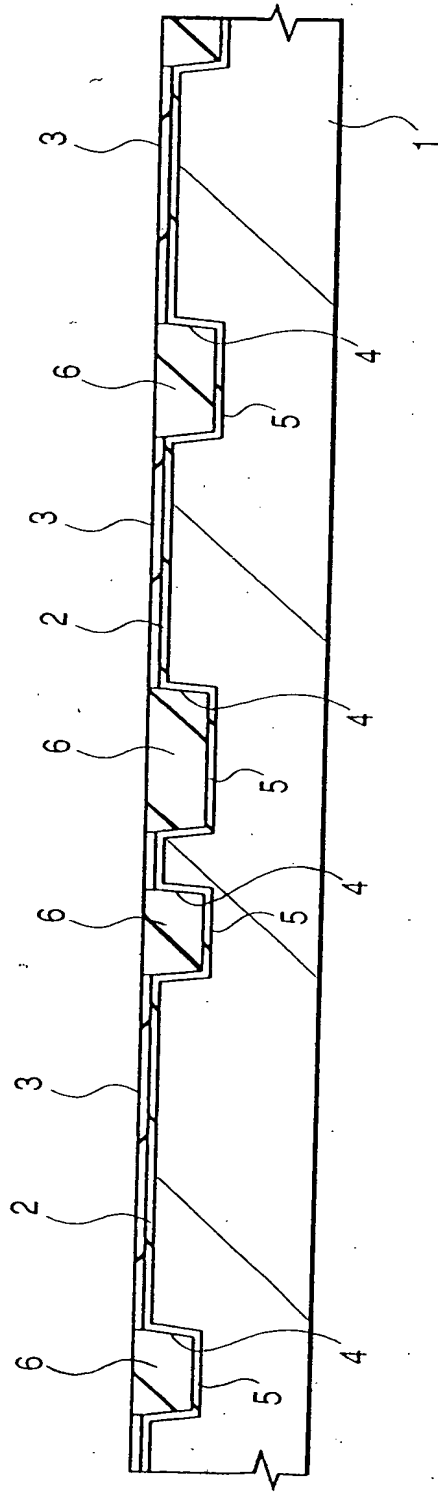


FIG. 5

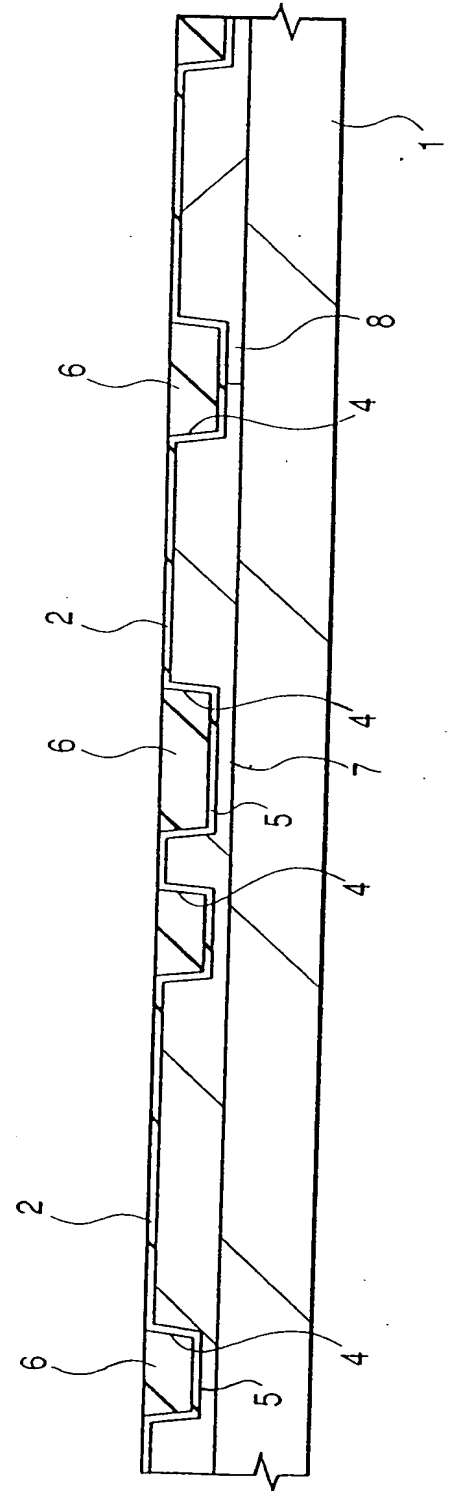


FIG. 6

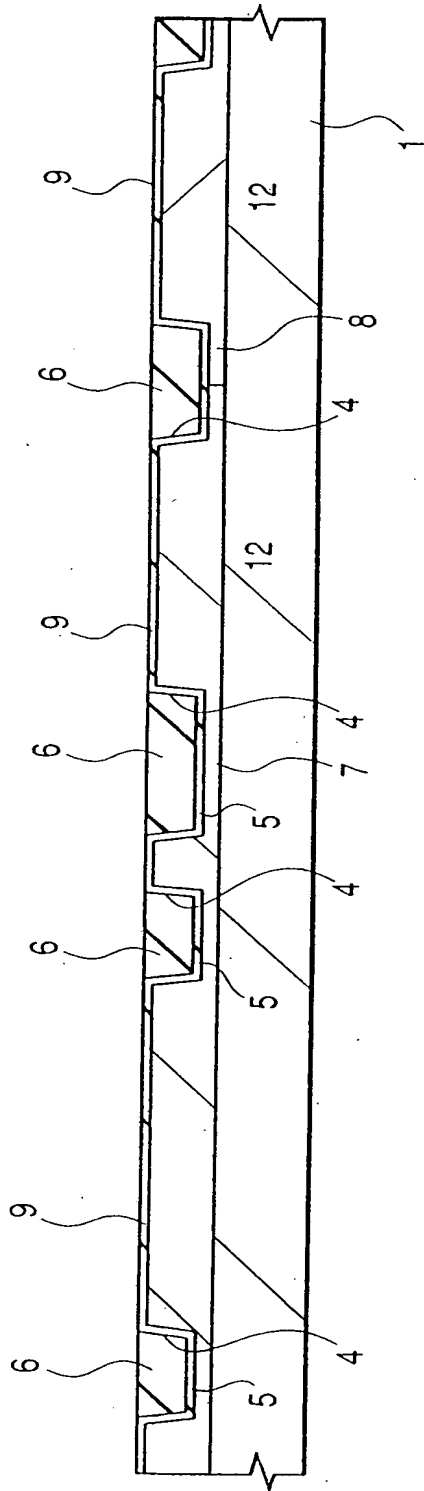
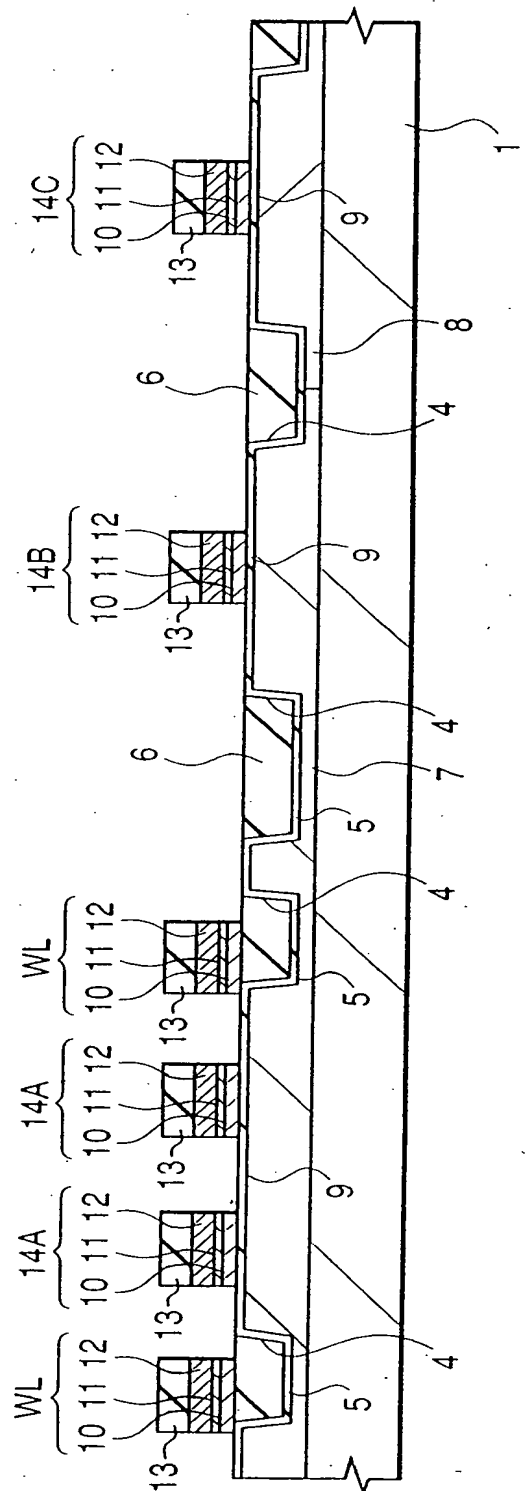


FIG. 7



5/21

FIG. 8

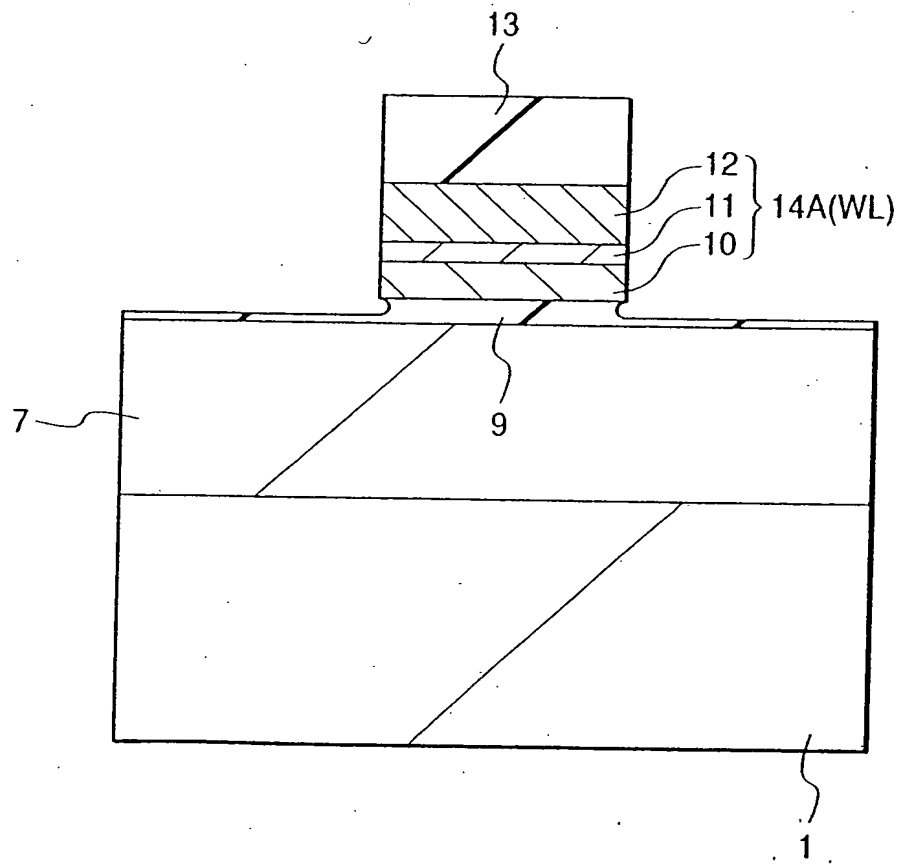


FIG. 9(a)

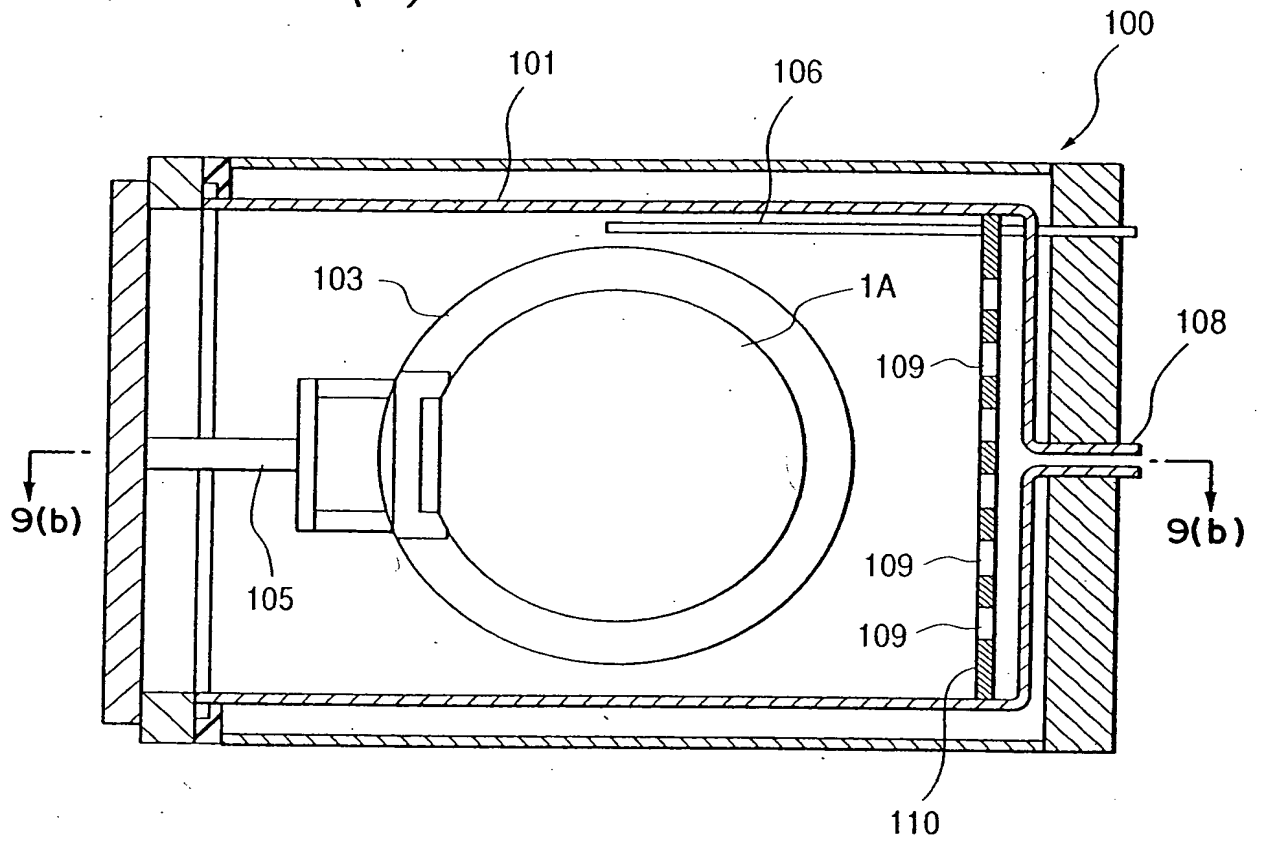


FIG. 9(b)

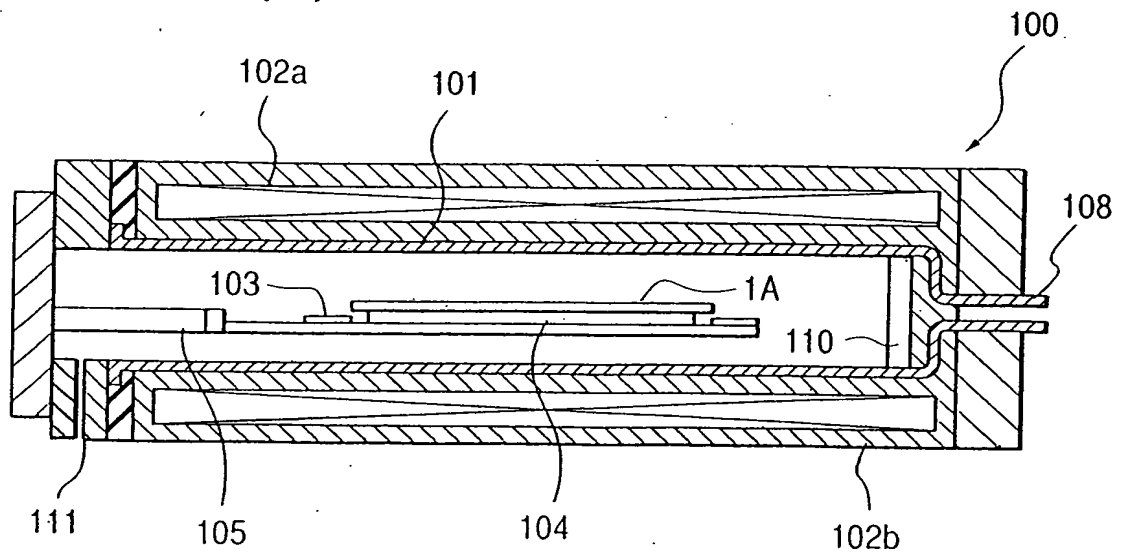


FIG. 10(a)

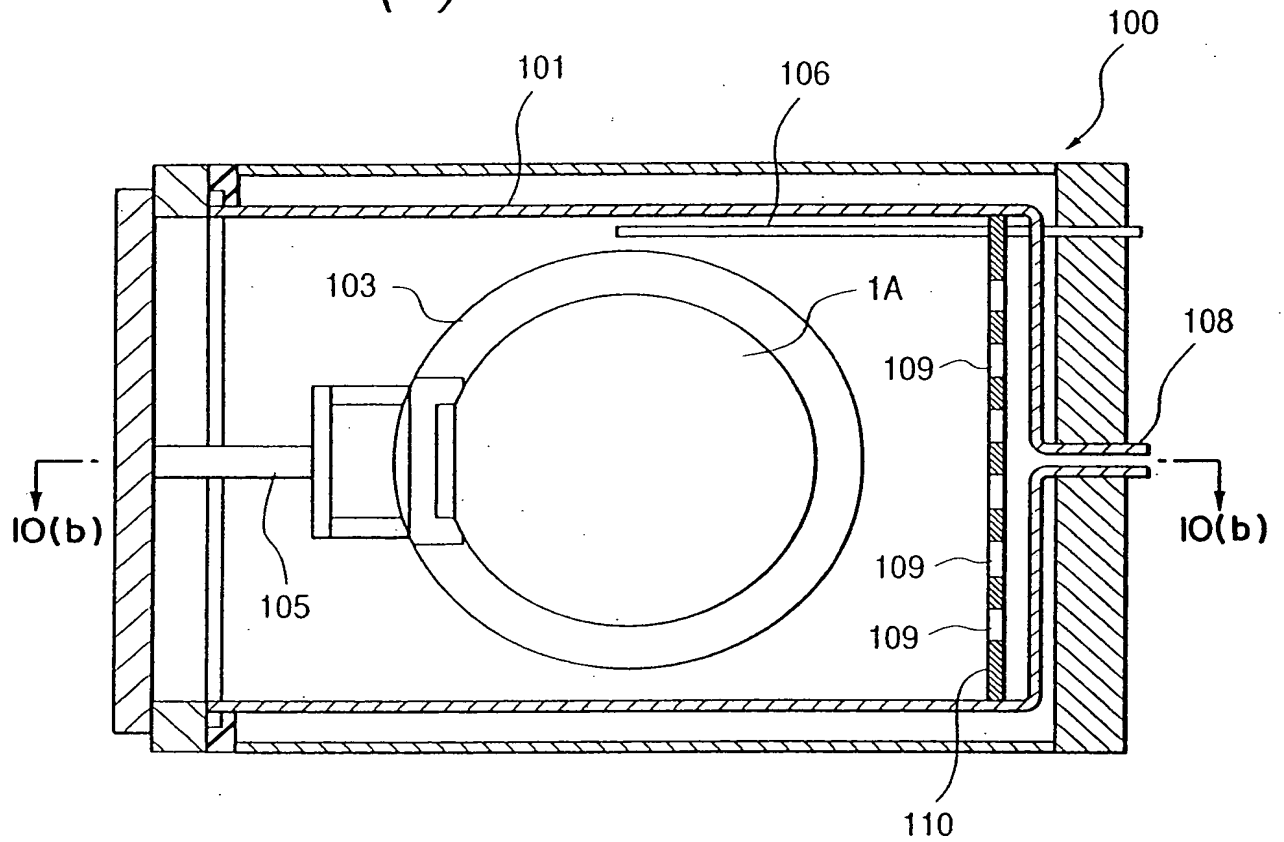


FIG. 10(b)

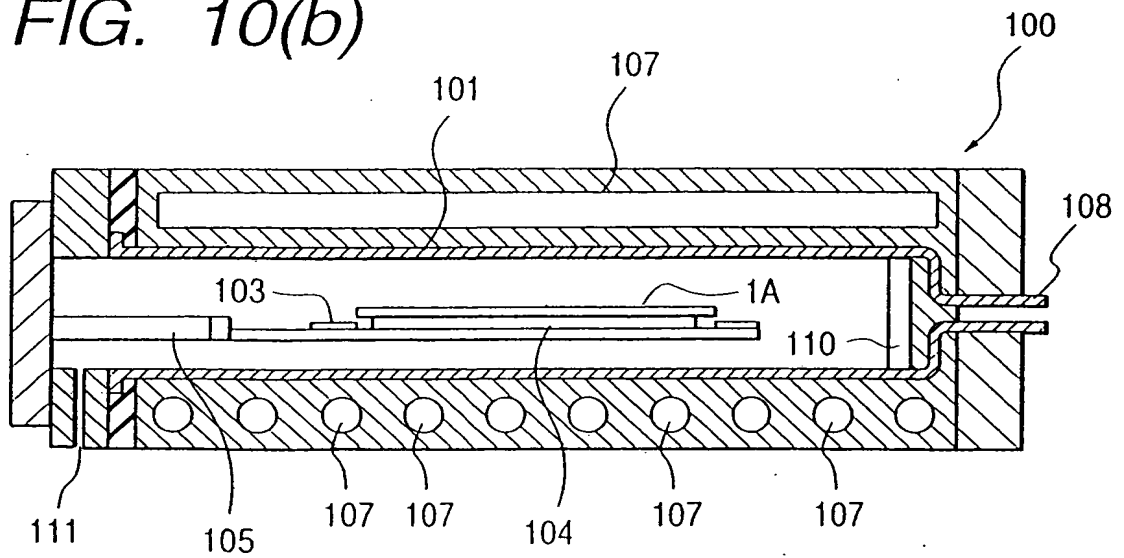


FIG. 11

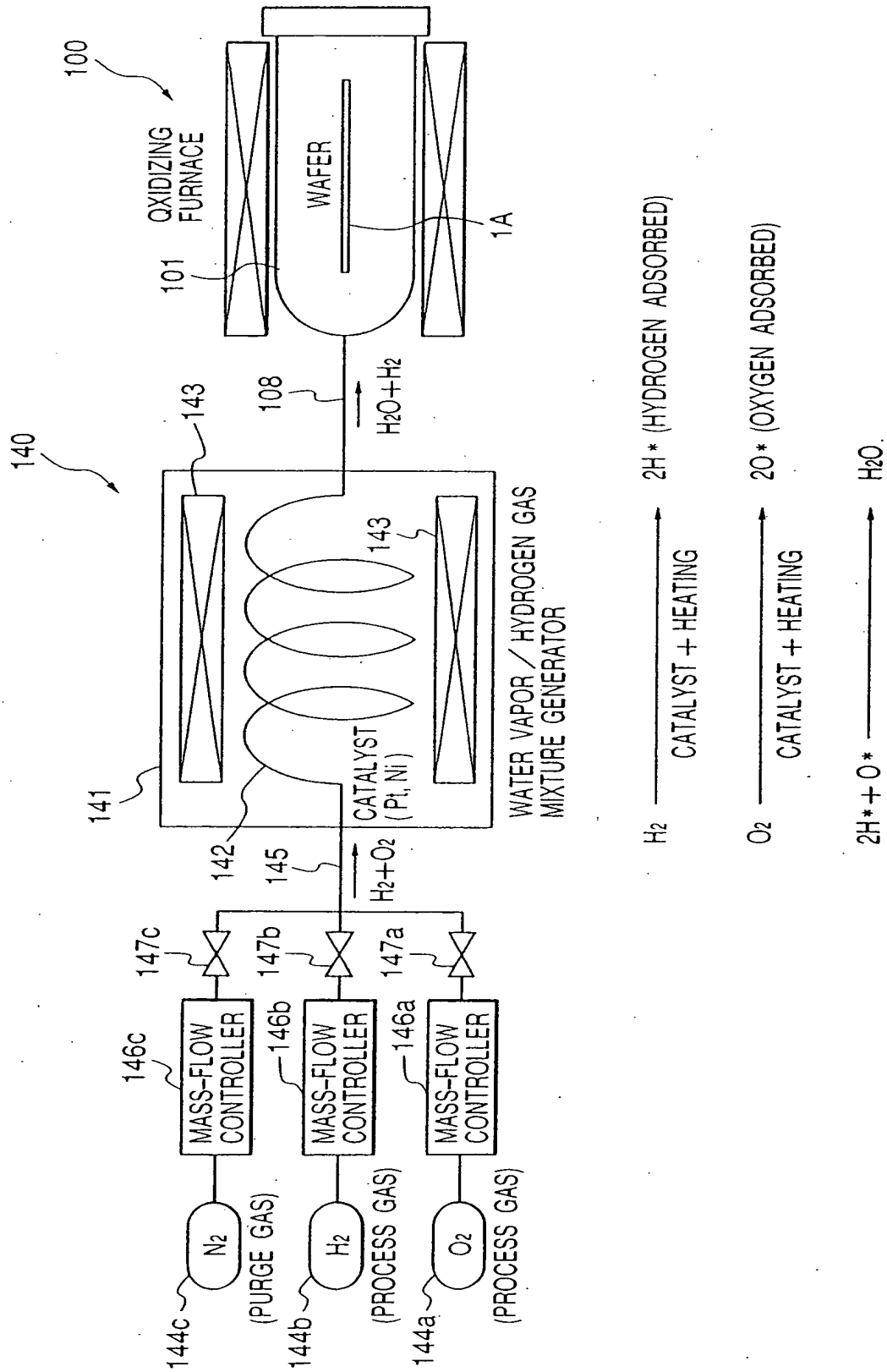
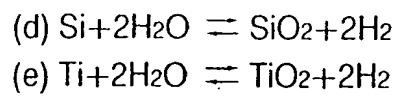
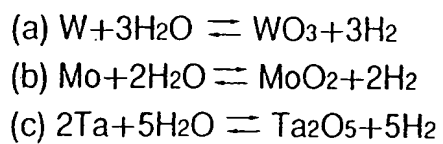
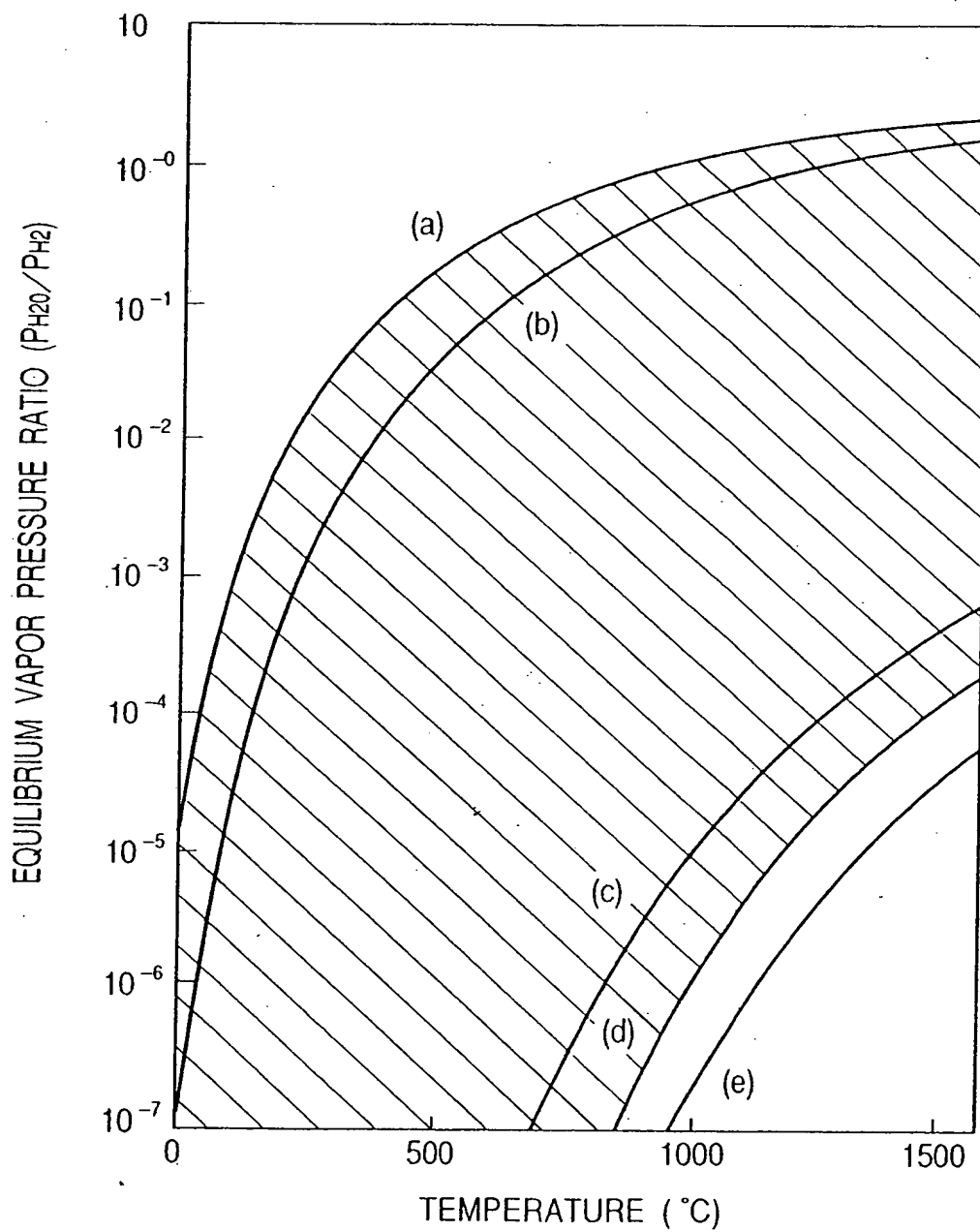


FIG. 12



10 / 21

FIG. 13

EVENT	LOADING OF WAFER	PURGING WITH N ₂	PURGING WITH H ₂	INTRODUCTION OF O ₂	ANNEALING	AFTER- PURGE	UNLOADING OF WAFER	REMARKS
TIME	55"	30"	t ₁	15"	OPTIONAL (SEVERAL MIN)	2' 20"	65"	6' 10" + OPTIONAL
FLOW RATE OF N ₂								
FLOW RATE OF H ₂								
FLOW RATE OF O ₂								

t₁: TIME NECESSARY FOR COMPLETE EXCHANGE OF N₂ FOR H₂

FIG. 14

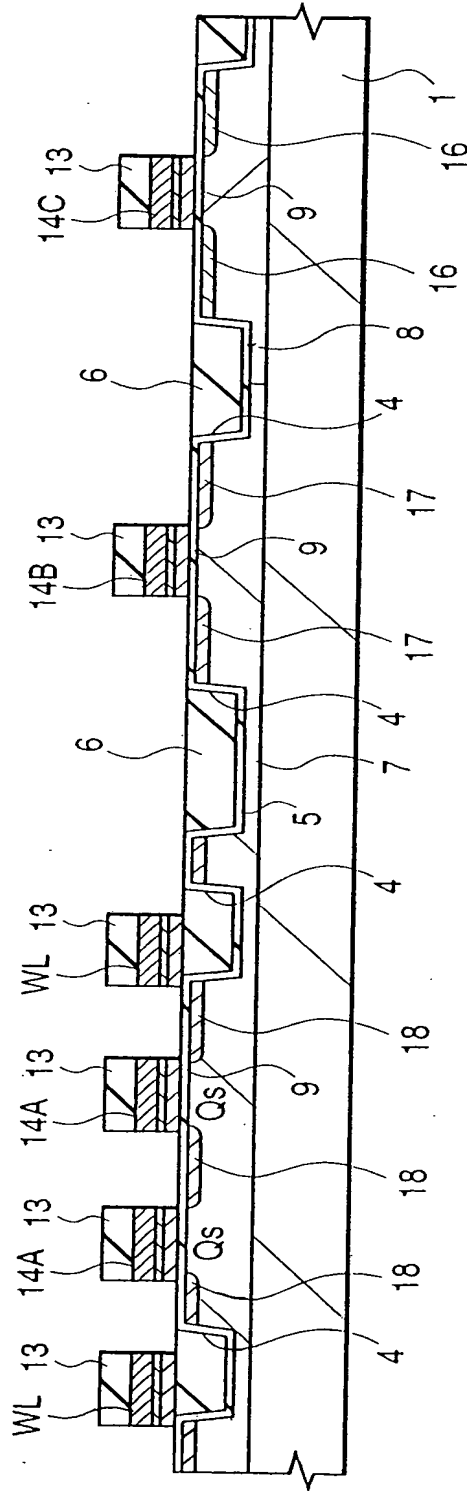


FIG. 15

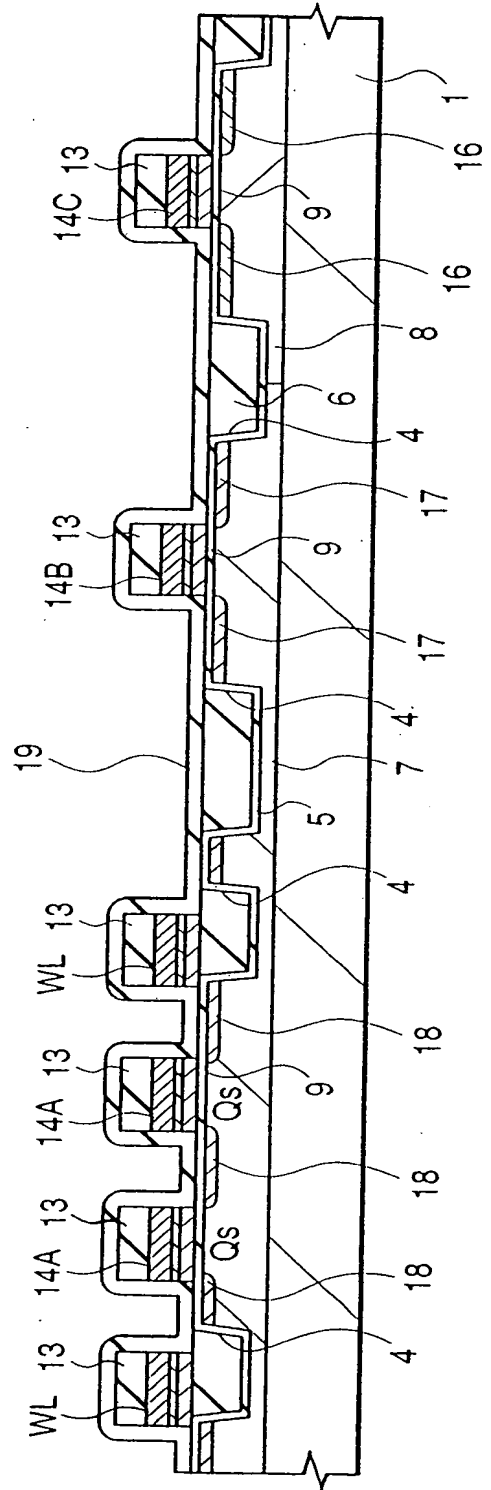


FIG. 16

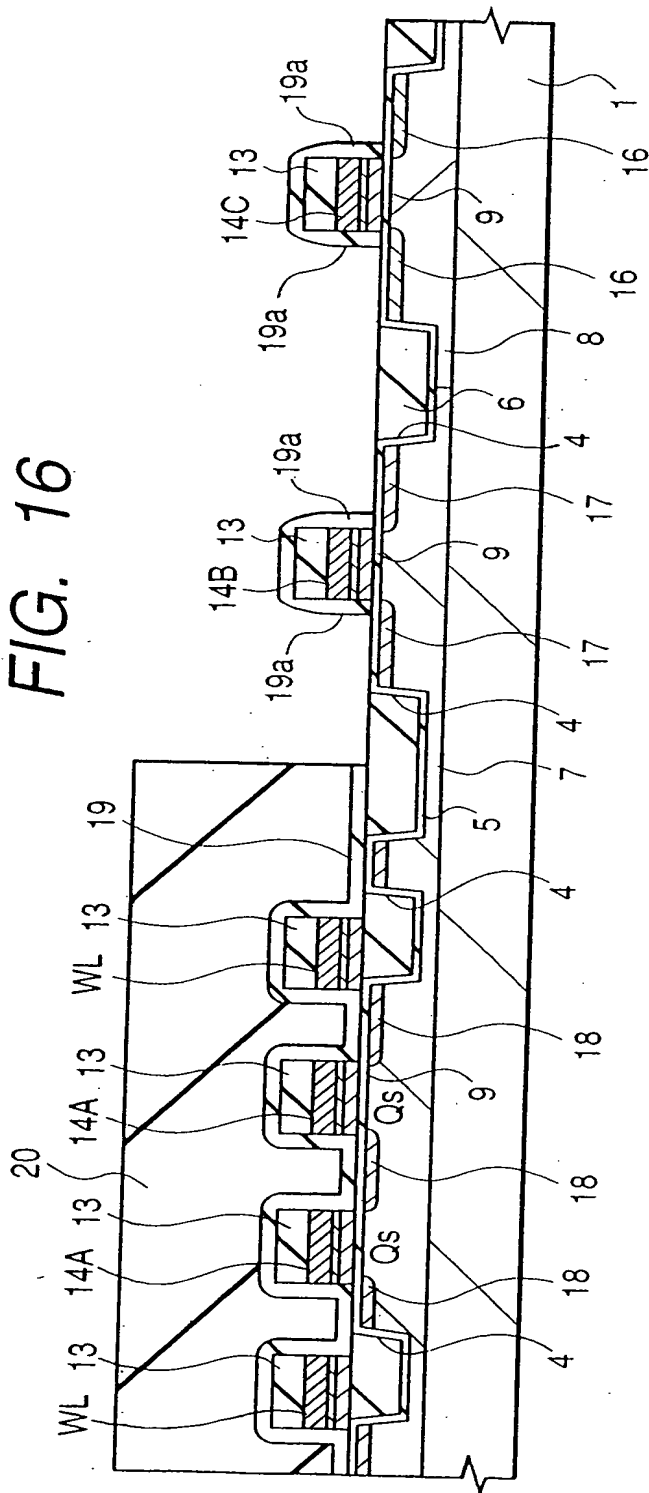


FIG. 17

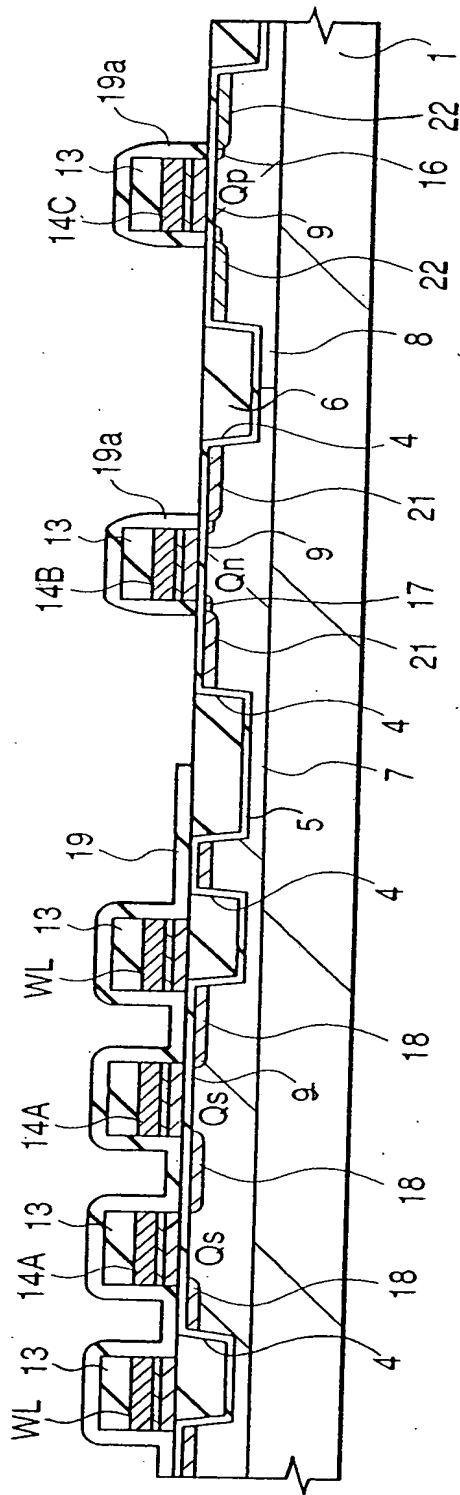


FIG. 19

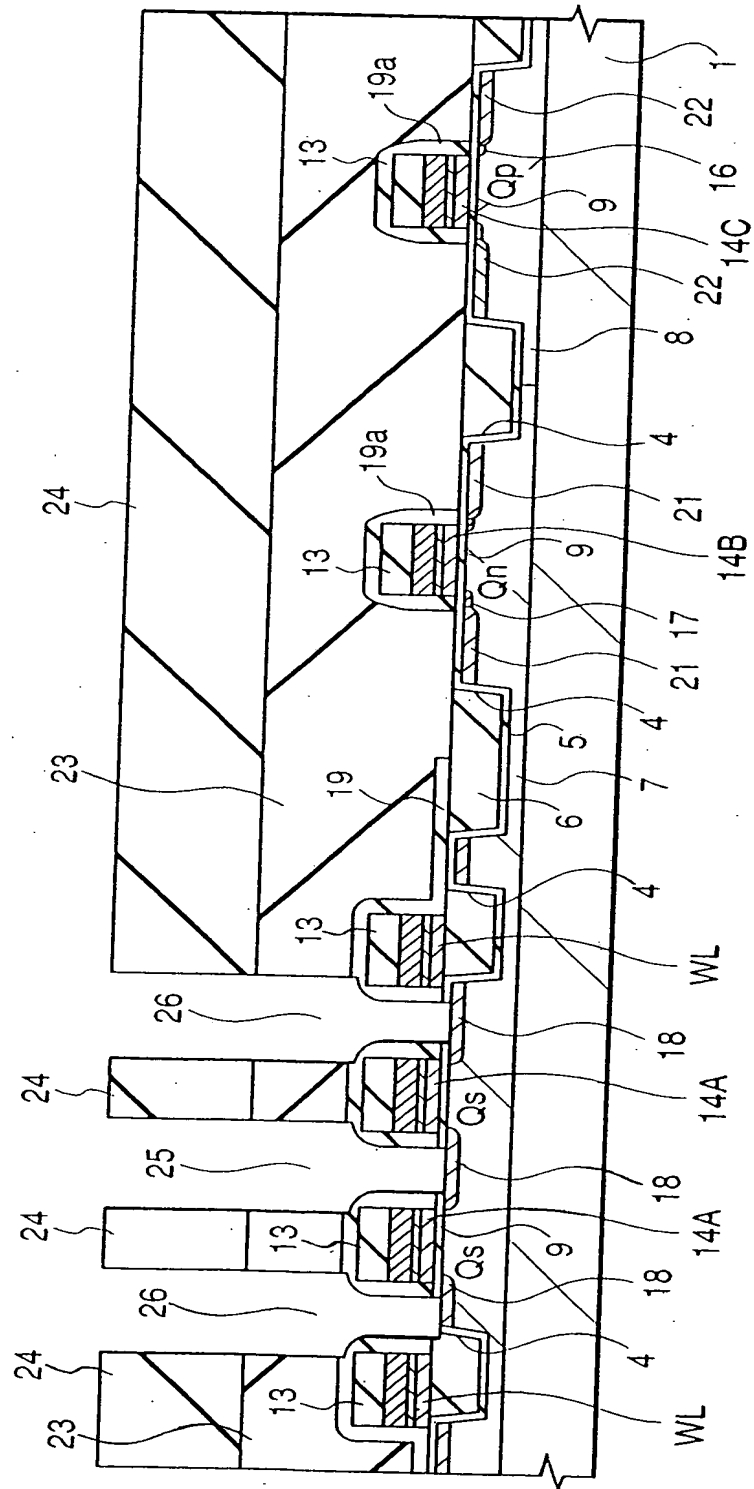


FIG. 21

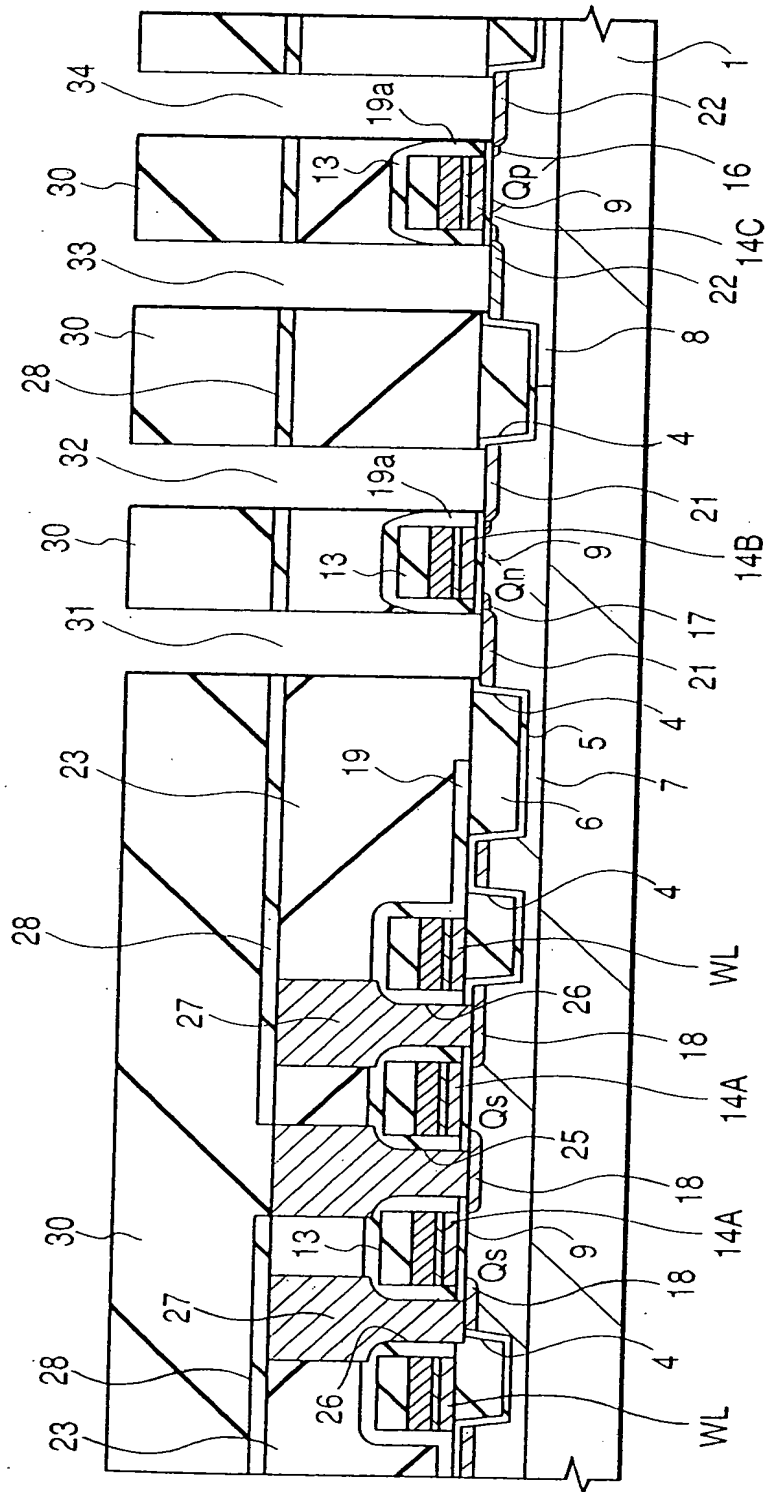


FIG. 22

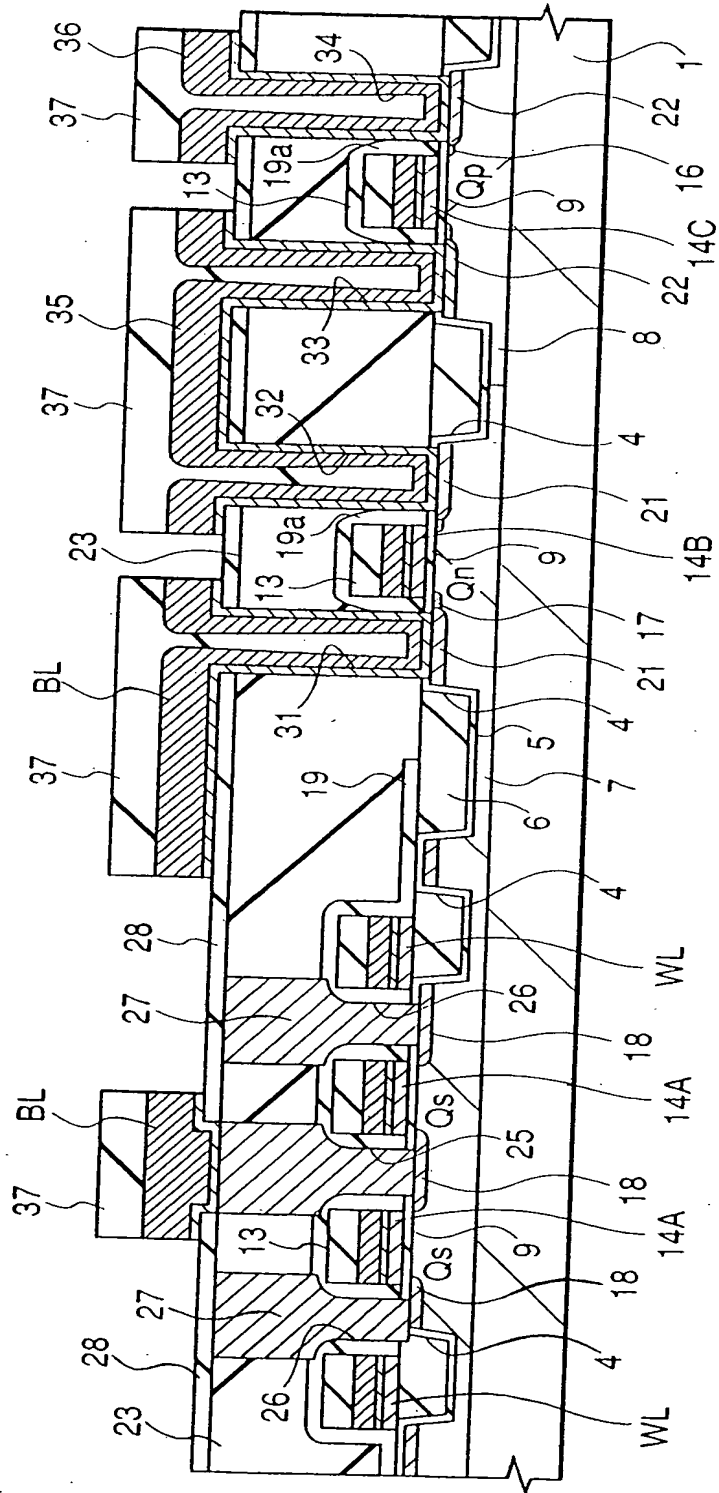


FIG. 24

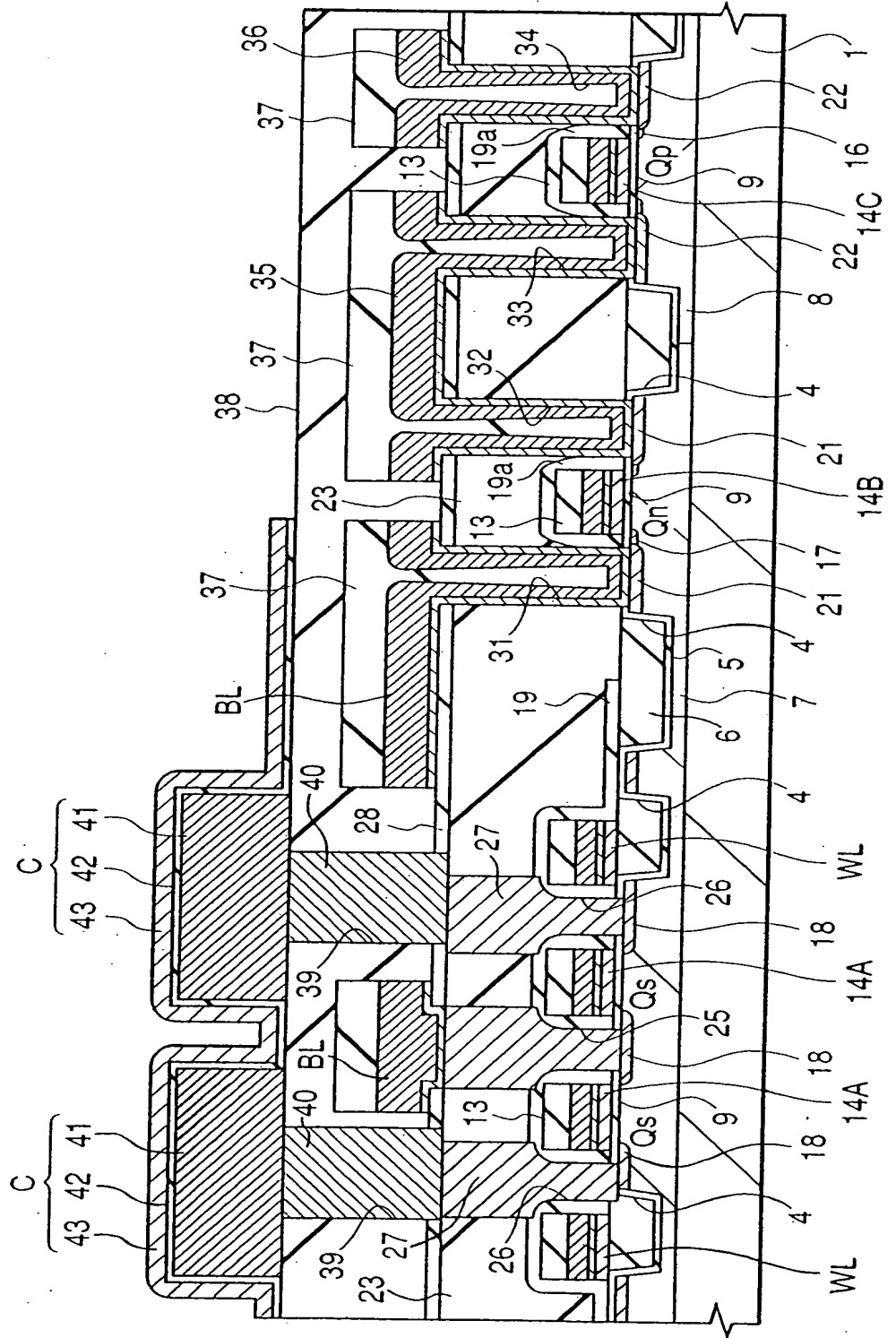


FIG. 25

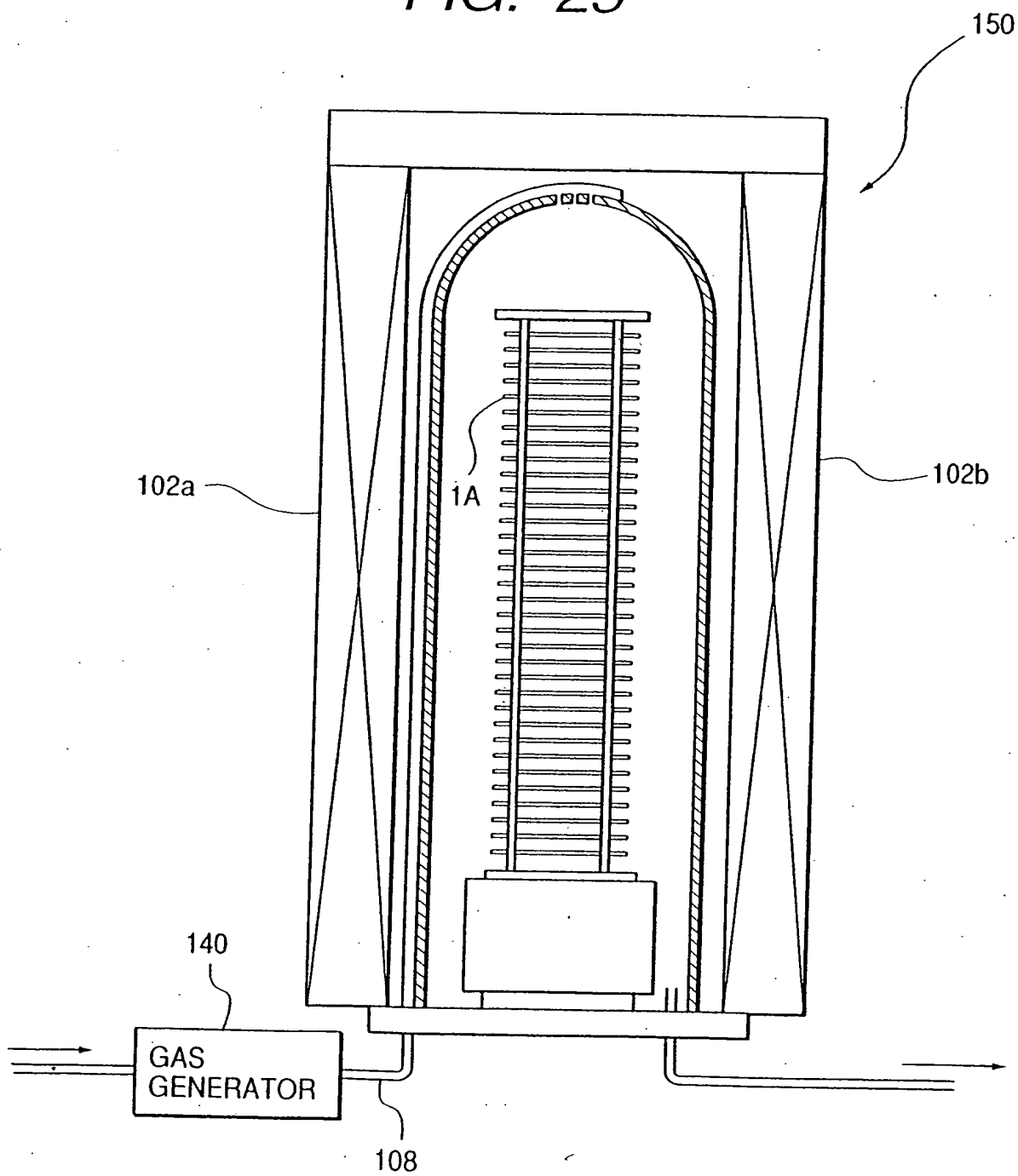


FIG. 26

EVENT	LOADING OF WAFER	PURGING WITH N ₂	PURGING WITH H ₂	INTRODUCTION OF O ₂	ANNEALING	AFTER- PURGE	UNLOADING OF WAFER	REMARKS
TIME	10'	1'	t ₂	15"	OPTIONAL (SEVERAL MIN)	2' 20"	10'	23' 40" + OPTIONAL
FLOW RATE OF N ₂								
FLOW RATE OF H ₂								
FLOW RATE OF O ₂								

t₂: TIME NECESSARY FOR COMPLETE EXCHANGE OF N₂ FOR H₂